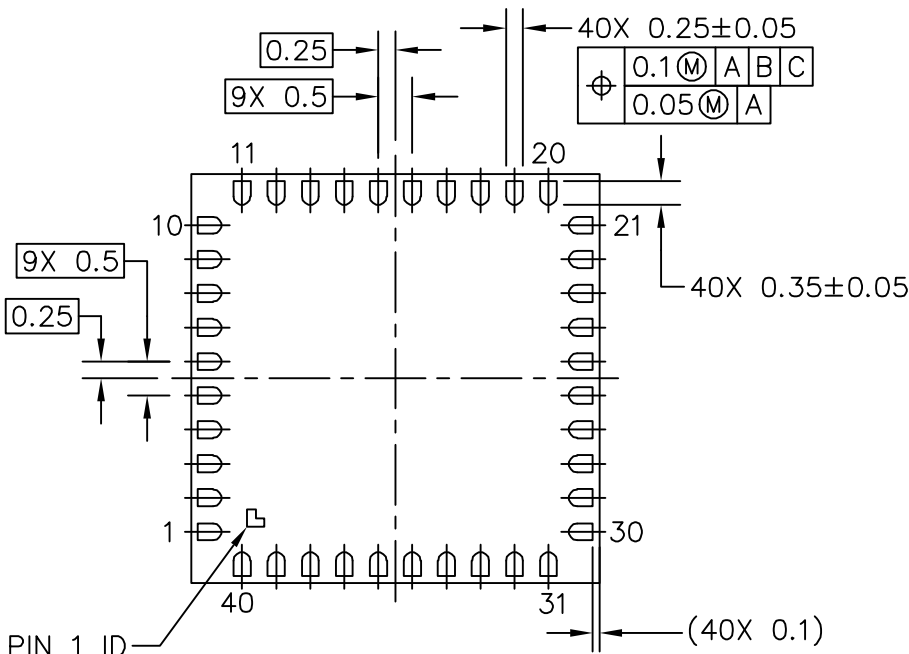
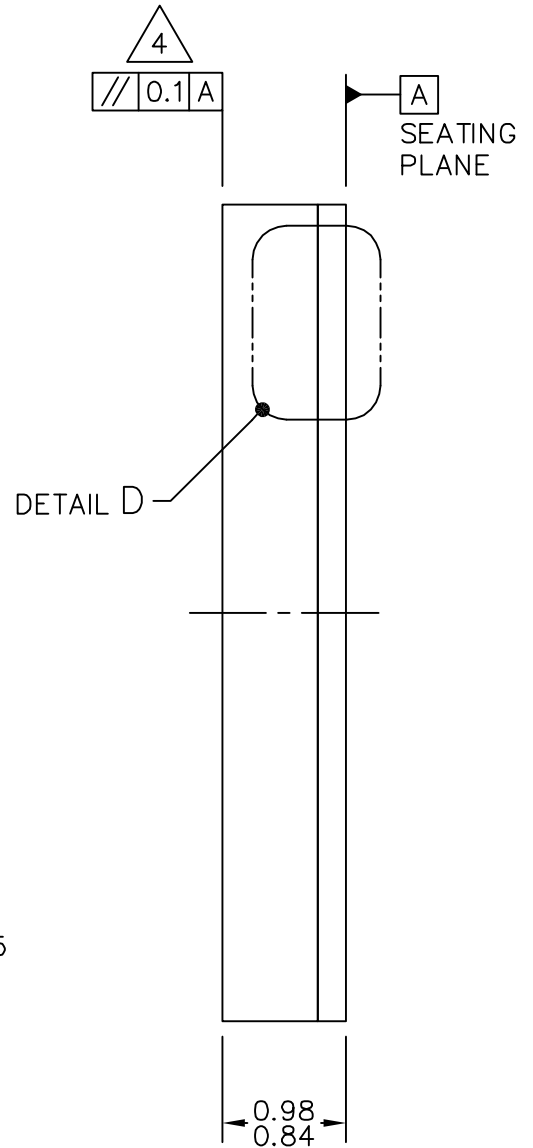
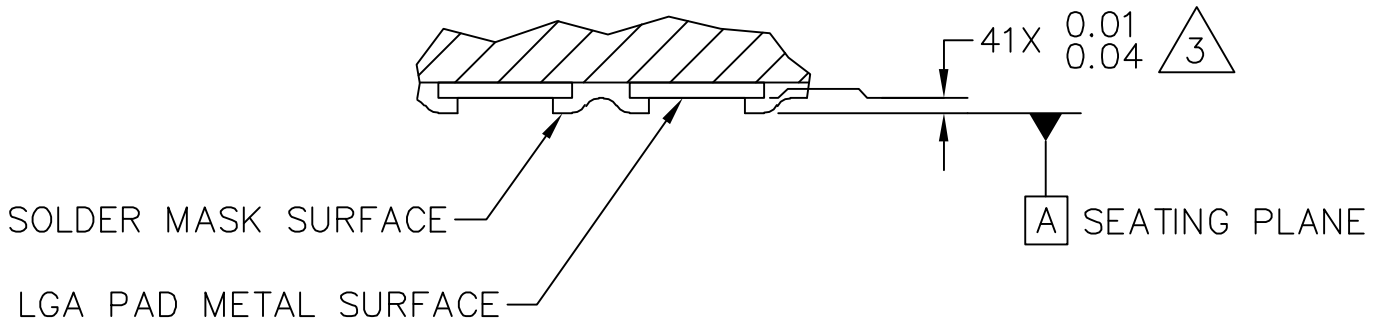


TOP VIEW



BOTTOM VIEW

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TITLE: LGA, THIN PROFILE, FINE PITCH, 40 I/O, 6 X 6 PKG, 0.5 MM PITCH (MAP)	DOCUMENT NO: 98ASA00388D	REV: A
	STANDARD: NON-JEDEC	
	SOT1646-1	08 JAN 2016



DETAIL D
VIEW ROTATED 90° CW

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		STANDARD: NON-JEDEC	
		SOT1646-1	08 JAN 2016



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. DIMENSION APPLIES TO LEADS, AND CENTER GROUND FLAG.

4. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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